

ELECTRONIC COMPONENT MOUNTING DEVICE AND ELECTRONIC COMPONENT MOUNTING METHOD

ABSTRACT

An electronic component mounting device (1) comprises: an electronic component supply
5 unit (20) that supplies an electronic component having a bump electrode (EB); a transfer stage (31)
that accumulates a flux (FX); a mounting stage (41) on which a substrate (BD) is placed; a plurality
of heads that can each pick up an electronic component (CP); and a control unit (10) that controls
movement of the plurality of heads. The control unit (10) is configured so as to cause each of
the plurality of heads to function as a dipping head that dips the bump electrode (EB) of the
10 electronic component (CP) into the flux (FX) accumulated on the transfer stage (31), or as a
bonding head that mounts the electronic component (CP) to the substrate (BD) on the mounting
stage (41) with the bump electrode (EB) interposed therebetween.

Representative drawing: FIG. 1